AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): ~~Method~~ A method for producing parts for passive electronic components ~~according to which~~comprising:

- producing a laminated strip ~~(1, 10, 13, 100) is produced which is constituted by at least one stack of~~ having at least one stack formed by alternately stacking a thin and fragile metal strip ~~(2, 21, 210)~~ and a layer of an adhesive material, and

- ~~and~~ forming at least one part ~~(6, 6', 16A, 16B, 16C, 16D; 54; 100)~~ for the passive electronic components ~~is cut from~~out of the laminated strip ~~(1, 10, 13, 100)~~ by cutting the laminated strip,

- ~~characterised in that~~wherein the cutting ~~operation~~ of the laminated strip ~~is carried out using a method which~~ comprises at least one step involving etching by ~~means of~~ sandblasting.

2. (currently amended): ~~Method~~ The method according to claim 1, ~~characterised in that~~wherein the layer of ~~an~~ adhesive material of the at least one stack is a layer ~~(3, 31, 310)~~ of a fragile and hard adhesive material.

3. (currently amended): ~~Method~~ The method according to claim 1, ~~characterised in that~~wherein the thin and fragile metal strip of the at least one stack ~~of thin and fragile metal strips and a layer of an adhesive material~~ is constituted by a material selected from the following

alloys: nanocrystalline magnetic alloys, fragile magnetic alloys of iron-cobalt, iron-platinum, iron-silicon, iron-nickel, fragile nickel-chromium alloys, fragile molybdenum alloys and fragile tungsten alloys.

4. (currently amended): The method~~Method~~ according to claim 1, ~~characterised in that, in order to carry out at least one step involving etching by means of sandblasting, there is arranged,~~wherein prior to the etching by sandblasting, arranging, on a face of the laminated strip ~~(1, 10, 13, 100)~~, a cover ~~(4, 14, 40, 400)~~ composed of a material which is resistant to sandblasting, the cover comprising at least one opening ~~(7, 17, 70, 700)~~ having at least one shape ~~according to which it is desirable to etch the at least one laminated strip~~.

5. (currently amended): The method~~Method~~ according to claim 4, ~~characterised in that~~wherein the cover ~~(4, 14, 40, 400)~~ is a steel strip which is resistant to ~~etching by means of~~ sandblasting.

6. (currently amended): The method~~Method~~ according to claim 4, ~~characterised in that~~wherein the cover ~~(4, 14, 40, 400)~~ is constituted by a resilient layer.

7. (currently amended): The method~~Method~~ according to claim 6, ~~characterised in that~~further comprising depositing the resilient layer ~~is a layer of paint deposited by means of~~ serigraphy, wherein the resilient layer is a layer of paint.

8. (currently amended): The method~~Method~~ according to claim 6, wherein~~characterised in that~~ the resilient layer is a layer of resilient photosensitive resin formed by exposing the resilient photosensitive resin~~which is exposed~~ to light radiation through a mask which comprises appropriate cut-outs, and developing the resilient photosensitive resin~~which is developed~~ by ~~means of~~ immersion in a bath before the etching by ~~means of~~ sandblasting is performed.

9. (withdrawn): Method according to claim 1, characterised in that the laminated strip (10, 100) is constituted by at least two alternate stacks (11, 12, 110, 120) of thin metal strips and layers of a fragile and hard adhesive material, the at least two alternate stacks being superimposed and separated by means of an adhesive layer (33, 330), at least a portion of which is constituted by a resilient material which is resistant to etching by means of sandblasting.

10. (currently amended): The method~~Method~~ according to claim 1, ~~characterised in that~~wherein, ~~in order to carry~~prior to carrying out the etching by ~~means of~~ sandblasting, bonding the laminated strip ~~(1, 10, 13, 100) is adhesively bonded~~ to a support strip or plate ~~(5, 15, 50, 51, 500)~~.

11. (currently amended): The method~~Method~~ according to claim 10, ~~characterised in that~~wherein, after cutting by sandblasting, separating the cut laminated strip ~~(13) and~~ from the support strip ~~(15) are separated~~.

12. (currently amended): The method~~Method~~ according to claim 10, ~~characterised in that~~wherein, ~~in order to carry~~prior to carrying out the etching by ~~means of~~ sandblasting, placing

the laminated strip ~~is placed so as to be arranged on~~ and the support strip in a sandblasting etching chamber comprising at least one sandblasting nozzle which projects a jet of abrasive particles, and ~~a relative movement of~~moving the laminated strip and the at least one sandblasting nozzle ~~is carried out~~ in order to pass over the surface of the laminated strip with the jet of abrasive particles.

13. (currently amended): The method~~Method~~ according to claim 1, wherein~~characterised in that~~ a plurality of parts ~~(16A, 16B, 16C and 16D)~~ for electronic components are formed out of the laminated strip by etching, the plurality of parts being~~which are~~ connected to each other by ~~means of~~ attachment points ~~(19A, 19B, 19C and 19D) are etched on the laminated strip (13, 13')~~, and ~~in that the various parts~~wherein the plurality of parts are separated after etching.

14. (currently amended): The method~~Method~~ according to claim ~~1~~2, ~~characterised in that~~wherein the fragile and hard material is an epoxy adhesive.

15. (currently amended): The method~~Method~~ according to claim 10, ~~characterised in that~~wherein the support strip is a strip comprising a layer ~~(52)~~ of polymer and a layer ~~(53)~~ of conductive material such as copper.

16. (withdrawn): Method according to claim 15, characterised in that the support strip (51) further comprises, before cutting by means of sandblasting, at least one electronic component which is protected during the sandblasting cutting operation by means of a layer of resilient material.

17. (withdrawn): Part which can be produced by the method according to claim 1, characterised in that it is a core of a passive inductive electronic component.

18. (withdrawn): Part according to claim 17, characterised in that it comprises an air gap.

19. (withdrawn): Part according to claim 17, characterised in that it is a torus having a thickness of less than 1 mm.

20. (withdrawn): Part according to claim 17, characterised in that it comprises at least two parts having different thicknesses.

21. (withdrawn): Part which can be produced using the method according to claim 1, characterised in that it is a fitting for an electrical capacitor.

22. (withdrawn): Part which can be produced using the method according to claim 1, characterised in that it constitutes an electrical resistor.

23. (withdrawn): Plate (51) which is intended to be incorporated in a printed circuit and which is constituted by a layer (53) of conductive material and a layer (52) of resilient polymer material, to which there is adhesively-bonded a passive electronic component part (54) which is cut from a laminated strip, optionally comprising at least one additional electronic component which can be produced using the method according to claim 15.

24. (currently amended): ~~Method~~ A method for producing a passive inductive electronic component ~~of the type~~ comprising:

forming a part which is cut from a laminated strip constituted by a stack of thin metal strips of a magnetic alloy,

~~characterised in that~~wherein the part is produced using the method according to claim 1, and

further comprising ~~at least one~~ winding and coating of the component with a protective material ~~are carried out~~.

25. (currently amended): ~~Method~~ A method for producing a passive electronic component which is capacitive or resistive, comprising:

forming a part which is cut from a laminated strip constituted by a stack of thin metal strips and ~~means~~ a portion for electrical connection,

wherein~~characterised in that~~ the part is produced using the method according to claim 1, and

further comprising producing the electrical connection ~~means~~ portion~~are produced~~ and coating the component ~~is coated~~ with a protective material.

26. (withdrawn): Method for producing a printed circuit comprising at least one passive electronic component which comprises at least one part which is constituted by a laminated metal material, characterised in that there is stacked and adhesively-bonded at least one plate according to claim 23 and at least one plate comprising a layer of polymer material.